



#### SCIENTECH

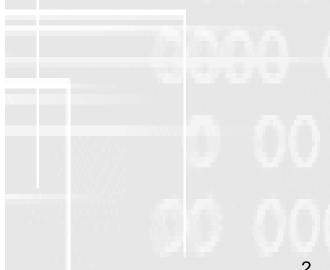
# (3583)

2021/9/2

# Safe Harbor Statement



- This Presentation contains certain forward-looking statements that are ٠ based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

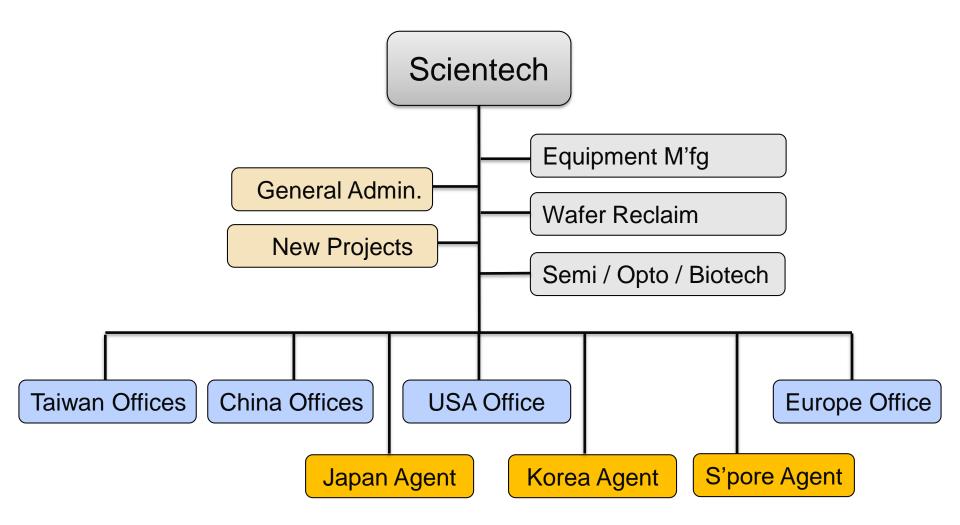


# Scientech Corp (3583: TT)

| Company<br>Establishment | 1979/10/17  |                                   |       |
|--------------------------|---|-----------------------------------|-------|
| IPO                      | 2013/3/12   |                                   | . 0.  |
| Capital                  | NT\$ 811 Million                                      |                                   | 2000  |
| Chairman                 | H.L. Hsieh  |                                   | 500 ( |
| CEO                      | M.T. Hus  |                                   | 100   |
| Products                 | Equipment Manufacturing<br>Trading(Agent/Distributor) | <ul> <li>Wafer Reclaim</li> </ul> |       |

# Organization





4 CONFIDENTIAL



Products

Future

Prospect

# **Income Statement**

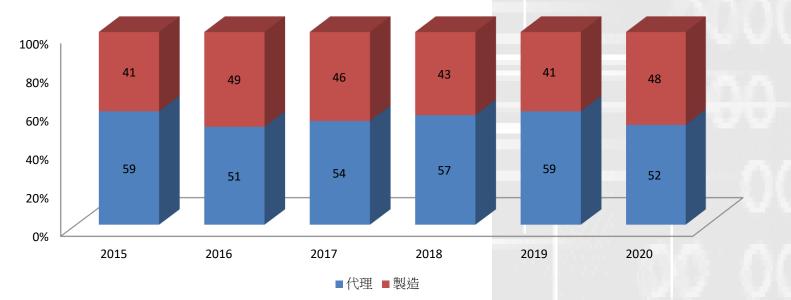


|                           | 1     | 1     | 1     |       | 1     |         |
|---------------------------|-------|-------|-------|-------|-------|---------|
| Units: NT \$ M            | 2016  | 2017  | 2018  | 2019  | 2020  | 2021/H1 |
| Revenues                  | 3,495 | 3,539 | 3,988 | 3,949 | 3,580 | 1,958   |
| Gross Profit              | 1,178 | 1,251 | 1,448 | 1,384 | 1,456 | 663     |
| Operating Expenses        | 835   | 829   | 935   | 997   | 991   | 472     |
| Operating Income          | 343   | 423   | 514   | 387   | 465   | 191     |
| Other Income and Expenses | 21    | (8)   | 26    | 16    | (76)  | 16      |
| Income Before Tax         | 363   | 415   | 540   | 403   | 389   | 207     |
| Net Income                | 292   | 328   | 418   | 323   | 305   | 167     |
| EPS                       | 3.60  | 4.05  | 5.16  | 4.02  | 3.80  | 2.08    |
| Gross Margin              | 34%   | 35%   | 36%   | 35%   | 41%   | 34%     |
| Operating Margin          | 10%   | 12%   | 13%   | 10%   | 13%   | 10%     |
| Income Before Tax margin  | 10%   | 12%   | 14%   | 10%   | 11%   | 11% 6   |





| Units : %     | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | Gross<br>Margin  |
|---------------|------|------|------|------|------|------|------------------|
| Trading       | 59   | 51   | 54   | 57   | 59   | 58   | Below<br>Average |
| Manufacturing | 41   | 49   | 46   | 43   | 41   | 42   | Above<br>Average |







| Units:NT\$M                 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021/H1 |
|-----------------------------|------|------|------|------|------|---------|
| R&D Expenses                | 226  | 228  | 246  | 246  | 248  | 126     |
| Expenses as %<br>of Revenue | 6.5% | 6.4% | 6.2% | 6.2% | 6.9% | 6.4%    |

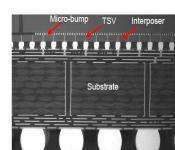


# What We Do



- Industries which we serve:
  - Semiconductor (Front-End and Advanced Packaging)
  - Compound Semiconductor
  - LED / Mini LED / Micro LED
  - Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)
  - Solar Cell / Battery
  - Biotech / Chemistry Analysis / Scientific Instrument,...



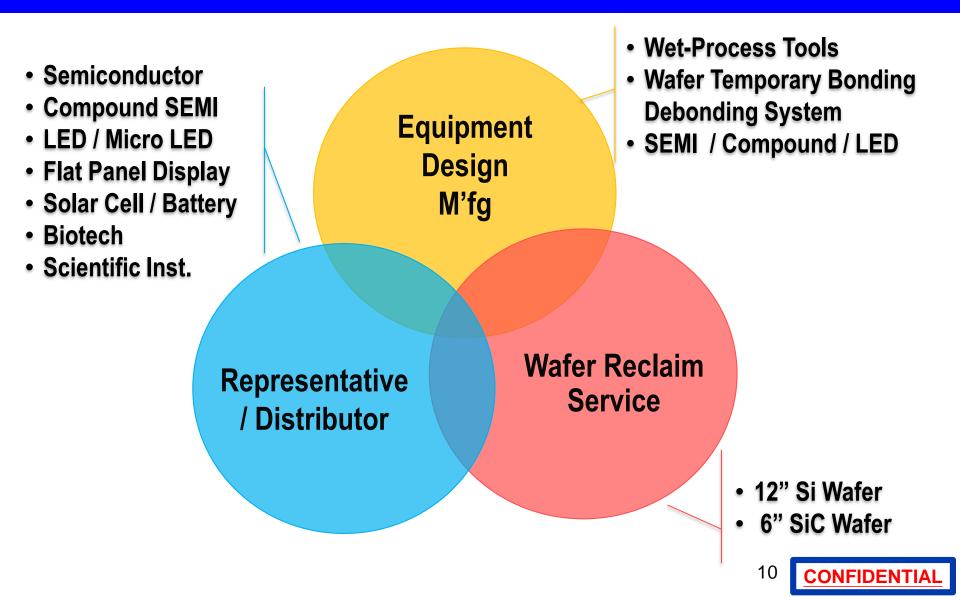








# Product and Technology



# Wafer Reclaim Service

• Scientech Corp.



- 12" Wafer Reclaim
  - Capacity: 120K / Month
  - Cu and Non-Cu Process
- SiC Post Slicing Process and Reclaim
  - Capacity: 3K / Month



11

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SCIENTECH

# Wet Process Equipment

• Scientech Corp.



- SCIENTECH
- Wet-Bench / Single-Wafer Wet Process Equipment
- Applications:
  - Advanced Packaging Process
  - Semiconductor Front-End Process
  - Compound Semiconductor
  - Microelectromechanical Systems (MEMS)
  - High-End LED Fully-Automatic Advanced Process





### Temporary Bonding Debonding System



• Scientech Corp.



- SCIENTECH
- Temporary Bonding Debonding System (TBDB)
- Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED
  - Temporary Bonding System
  - Temporary Debonding System
  - Release Layer Formation System
  - Carrier (Glass) Recycling System





13 CONFIDENTIA

#### Trading (Agent/Distributor)





### Future Prospect

# The Growing Market Science

- In the next 10-20 years, the overall semiconductor industry will grow 5%-6% (CAGR) which is over than the global GDP growth rate 2.5%-3%
- The continuous development of 12" semiconductor advanced process
  - Front-End : 5nm \ 3nm \ 2nm \ 1nm \
  - Advanced Packaging : Fan-Out 、 CoWoS (2.5D) 、 SolC(3D) 、 etc.
- The continuous expansion of China semiconductor fabs in recent years
- The demand of 8" semiconductor fab is higher than the supplying capacity
- Compound semiconductor :
  - The investments of electrical car and 5G are growing tremendously
  - The third generation of semiconductor arises. The demand of high power and high frequency semiconductor are growing rapidly.
- The new application of Mini LED & Micro LED starts and it will lead the LED industry grows again.

**Q & A** 





#### Thank You!